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Abstract

A small package is provided for a flash EEPROM memory. The small package uses terminals which are part of a bottom conductive layer of a circuit board. In this manner, the final package can be quite thin. The circuit board can be connected to the integrated circuits and passive devices and can be encapsulated in plastic or glued to a plastic cover. In this manner, a thin and relatively inexpensive package can be formed. Additionally, the circuit board can have testing connections which can be removed before forming the final package.

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